

PCN Number:	20171011001	PCN Date:	October 13, 2017
Title:	Datasheet for LMH1208		
Customer Contact:	PCN Manager	Dept:	Quality Services
Change Type:			
<input type="checkbox"/>	Assembly Site	<input type="checkbox"/>	Design
<input type="checkbox"/>	Assembly Process	<input checked="" type="checkbox"/>	Data Sheet
<input type="checkbox"/>	Assembly Materials	<input type="checkbox"/>	Part number change
<input type="checkbox"/>	Mechanical Specification	<input type="checkbox"/>	Test Site
<input type="checkbox"/>	Packing/Shipping/Labeling	<input type="checkbox"/>	Test Process
<input type="checkbox"/>		<input type="checkbox"/>	Wafer Bump Site
<input type="checkbox"/>		<input type="checkbox"/>	Wafer Bump Material
<input type="checkbox"/>		<input type="checkbox"/>	Wafer Bump Process
<input type="checkbox"/>		<input type="checkbox"/>	Wafer Fab Site
<input type="checkbox"/>		<input type="checkbox"/>	Wafer Fab Materials
<input type="checkbox"/>		<input type="checkbox"/>	Wafer Fab Process

Notification Details

Description of Change:

Texas Instruments Incorporated is announcing an information only notification. The product datasheet(s) is being updated as summarized below. The following change history provides further details.



LMH1208

SNLS569A – MARCH 2017 – REVISED SEPTEMBER 2017

Changes from Original (March 2017) to Revision A

Page

• Changed typical power consumption from 255 mW to 200 mW based on updated characterization data	1
• Changed description of RSV_L to clarify that RSV_L must be tied to a 2.5-V supply	5
• Changed NTps _{max} test condition max from 6 GHz to 50 MHz and < 20 mVp-p NOM to < 10 mVp-p	6
• Changed typical power dissipation based on updated complete characterization data	7
• Changed typical and maximum current dissipation based on updated complete characterization data	7
• Changed t _{R_F_SDI} minimum SD rise/fall time from 390 ps to 400 ps due to incorrect default settings	9
• Changed typical t _R /t _F of OUT0 from 35 ps to 45 ps	10
• Added PRBS10 pattern to clarify ADDJ _{CD} Test Condition	10
• Added SMBUS SCL min frequency per SMBus 2.0 specifications	10
• Added Figure 1 to clarify definition of SMBus Timing Parameters in <i>Recommended SMBus Interface Timing Specifications</i>	11
• Added typical characteristic curves for OUT0 VOD and de-emphasis vs. LMH1208 register settings	13
• Moved the <i>LMH1208 and LMH1228 Compatibility</i> section to the <i>Application Information</i> section	24
• Added default internal pullup and pulldown settings for 2-level strap pins in Figure 19	25
• Changed RSV_L pin setting to tie to 2.5-V supply instead of GND in Figure 19	25
• Changed Figure 40 to show RSV_L tied to 2.5-V supply	32
• Changed Figure 41 to show Pin 21 via to RSV_L pour (2.5 V) instead of VSS	35
• Added mechanical, thermal pad, and land pattern drawings to the <i>Package Option Addendum</i>	37

The datasheet number will be changing.

Device Family	Change From:	Change To:
LMH1208	SNLS569	SNLS569A

These changes may be reviewed at the datasheet links provided.

<http://www.ti.com/product/LMH1208>

Reason for Change:

To accurately reflect device characteristics.

Anticipated impact on Fit, Form, Function, Quality or Reliability (positive / negative):

No anticipated impact. This is a specification change announcement only. There are no changes to the actual device.

Changes to product identification resulting from this PCN:			
None.			
Product Affected:			
LMH1208RTVR	LMH1208RTVT		

For questions regarding this notice, e-mails can be sent to the regional contacts shown below or your local Field Sales Representative.

Location	E-Mail
USA	PCNAmericasContact@list.ti.com
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Asia Pacific	PCNAsiaContact@list.ti.com
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